



T4 Series

SNUBBERLESS™ & LOGIC LEVEL

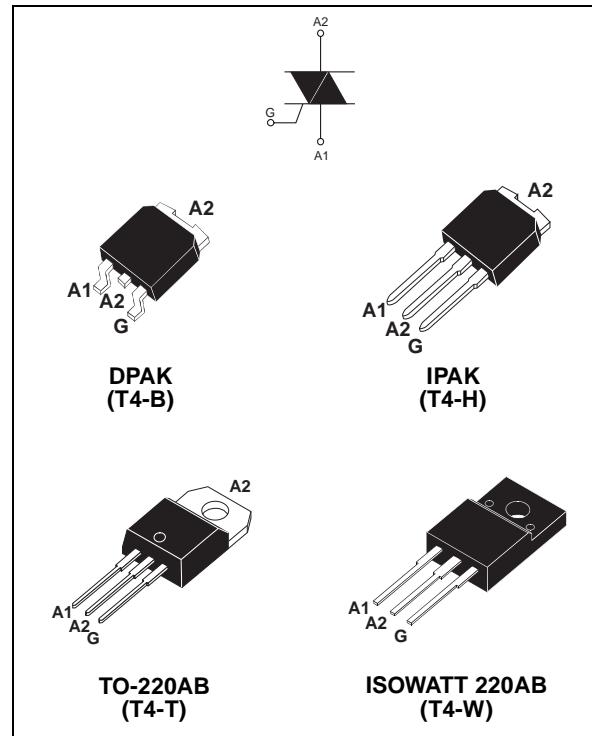
4A TRIACs

MAIN FEATURES:

Symbol	Value	Unit
$I_T(\text{RMS})$	4	A
$V_{\text{DRM}}/V_{\text{RRM}}$	600 to 800	V
$I_{\text{GTT}}(Q_1)$	5 to 35	mA

DESCRIPTION

Based on ST's Snubberless / Logic level technology providing high commutation performances, the T4 series is suitable for use on AC inductive loads. They are recommended for applications using universal motors, electrovalves.... such as kitchen aid equipments, power tools, dishwashers,... Available in a fully insulated package, the T4...-...W version complies with UL standards (ref. E81734).



ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter			Value	Unit
$I_T(\text{RMS})$	RMS on-state current (full sine wave)		DPAK / IPAK TO-220AB	4	A
	ISOWATT 220AB		$T_c = 110^\circ\text{C}$		
I_{TSM}	Non repetitive surge peak on-state current (full cycle, T_j initial = 25°C)	F = 50 Hz	t = 20 ms	30	A
		F = 60 Hz	t = 16.7 ms	31	
I^2t	I^2t Value for fusing	$t_p = 10 \text{ ms}$		5.1	A^2s
dl/dt	Critical rate of rise of on-state current $I_G = 2 \times I_{\text{GT}}$, $tr \leq 100 \text{ ns}$	F = 120 Hz	$T_j = 125^\circ\text{C}$	50	$\text{A}/\mu\text{s}$
I_{GM}	Peak gate current	$t_p = 20 \mu\text{s}$	$T_j = 125^\circ\text{C}$	4	A
$P_{\text{G(AV)}}$	Average gate power dissipation		$T_j = 125^\circ\text{C}$	1	W
T_{stg} T_j	Storage junction temperature range Operating junction temperature range			- 40 to + 150 - 40 to + 125	$^\circ\text{C}$

T4 Series

ELECTRICAL CHARACTERISTICS ($T_j = 25^\circ\text{C}$, unless otherwise specified)

Symbol	Test Conditions	Quadrant		T4			Unit
				T405	T410	T435	
I_{GT} (1)	$V_D = 12 \text{ V}$ $R_L = 30 \Omega$	I - II - III	MAX.	5	10	35	mA
V_{GT}		I - II - III	MAX.	1.3			V
V_{GD}	$V_D = V_{DRM}$ $R_L = 33 \text{ k}\Omega$ $T_j = 125^\circ\text{C}$	I - II - III	MIN.	0.2			V
I_H (2)	$I_T = 100 \text{ mA}$		MAX.	10	15	35	mA
I_L	$I_G = 1.2 I_{GT}$	I - III	MAX.	10	25	50	mA
		II		15	30	60	
dV/dt (2)	$V_D = 67 \% V_{DRM}$ gate open $T_j = 125^\circ\text{C}$		MIN.	20	40	400	V/ μs
(dI/dt)c (2)	(dV/dt)c = 0.1 V/ μs $T_j = 125^\circ\text{C}$		MIN.	1.8	2.7	-	A/ms
	(dV/dt)c = 10 V/ μs $T_j = 125^\circ\text{C}$			0.9	2.0	-	
	Without snubber $T_j = 125^\circ\text{C}$			-	-	2.5	

STATIC CHARACTERISTICS

Symbol	Test Conditions			Value	Unit	
V_{TM} (2)	$I_{TM} = 5.5 \text{ A}$	$t_p = 380 \mu\text{s}$	$T_j = 25^\circ\text{C}$	MAX.	1.6	V
V_{to} (2)	Threshold voltage		$T_j = 125^\circ\text{C}$	MAX.	0.9	V
R_d (2)	Dynamic resistance		$T_j = 125^\circ\text{C}$	MAX.	120	m Ω
I_{DRM}	$V_{DRM} = V_{RRM}$		$T_j = 25^\circ\text{C}$	MAX.	5	μA
I_{RRM}			$T_j = 125^\circ\text{C}$		1	mA

Note 1: minimum I_{GT} is guaranteed at 5% of I_{GT} max.

Note 2: for both polarities of A2 referenced to A1

THERMAL RESISTANCES

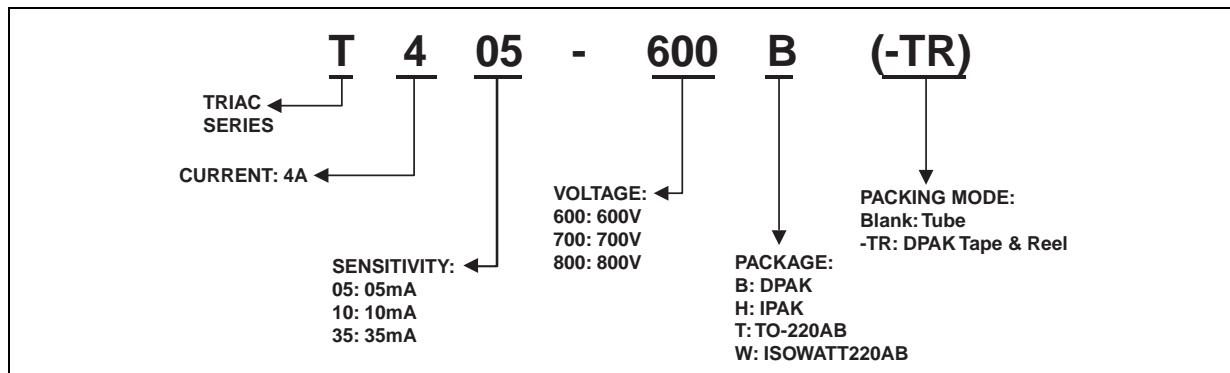
Symbol	Parameter			Value	Unit
$R_{th(j-c)}$	Junction to case (AC)		DPAK IPAK TO-220AB	2.6	°C/W
			ISOWATT220AB	4.0	
$R_{th(j-a)}$	Junction to ambient	$S = 0.5 \text{ cm}^2$	DPAK	70	°C/W
			TO-220AB ISOWATT220AB	60	
			IPAK	100	

S = Copper surface under tab

PRODUCT SELECTOR

Part Number	Voltage (xxx)			Sensitivity	Type	Package
	600 V	700 V	800 V			
T405-xxxB	X	X	X	5 mA	Logic level	DPAK
T405-xxxH	X	X	X	5 mA	Logic level	IPAK
T405-xxxT	X	X	X	5 mA	Logic level	TO-220AB
T405-xxxW	X	X	X	5 mA	Logic level	ISOWATT220AB
T410-xxxB	X	X	X	10 mA	Logic level	DPAK
T410-xxxH	X	X	X	10 mA	Logic level	IPAK
T410-xxxT	X	X	X	10 mA	Logic level	TO-220AB
T410-xxxW	X	X	X	10 mA	Logic level	ISOWATT220AB
T435-xxxB	X	X	X	35 mA	Snubberless	DPAK
T435-xxxH	X	X	X	35 mA	Snubberless	IPAK
T435-xxxT	X	X	X	35 mA	Snubberless	TO-220AB
T435-xxxW	X	X	X	35 mA	Snubberless	ISOWATT220AB

ORDERING INFORMATION



OTHER INFORMATION

Part Number	Marking	Weight	Base quantity	Packing mode
T4xx-yyyB	T4xxyyyB	0.3 g	75	Tube
T4xx-yyyB-TR	T4xxyyyB	0.3 g	2500	Tape & reel
T4xx-yyyH	T4xxyyy	0.4 g	75	Tube
T4xx-yyyT	T4xxyyyT	2.3 g	50	Tube
T4xx-yyyW	T4xxyyyW	2.1 g	50	Tube

Note: xx = sensitivity, yyy = voltage

T4 Series

Fig. 1: Maximum power dissipation versus RMS on-state current (full cycle).

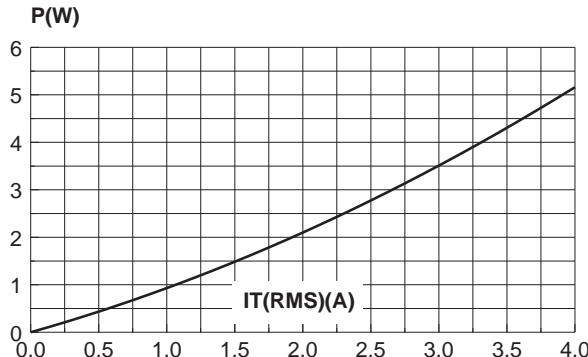


Fig. 2-2: RMS on-state current versus ambient temperature (printed circuit FR4, copper thickness: 35µm), full cycle.

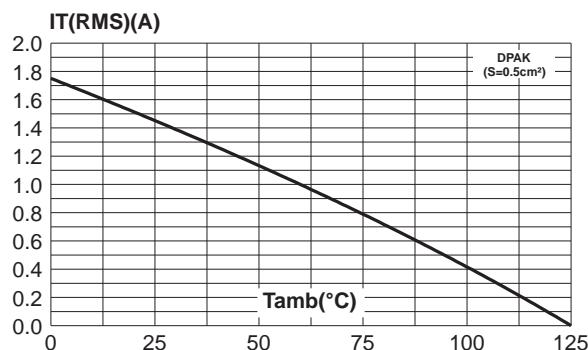


Fig. 4: Relative variation of gate trigger current, holding current and latching current versus junction temperature (typical values).

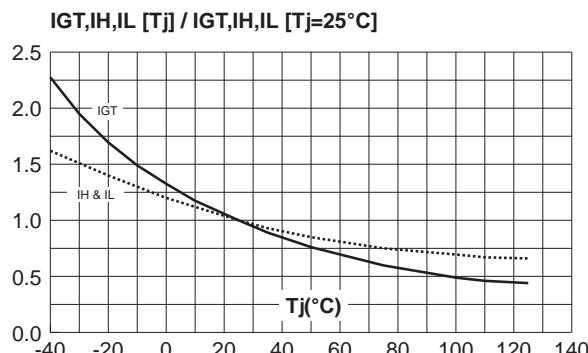


Fig. 2-1: RMS on-state current case versus temperature (full cycle).

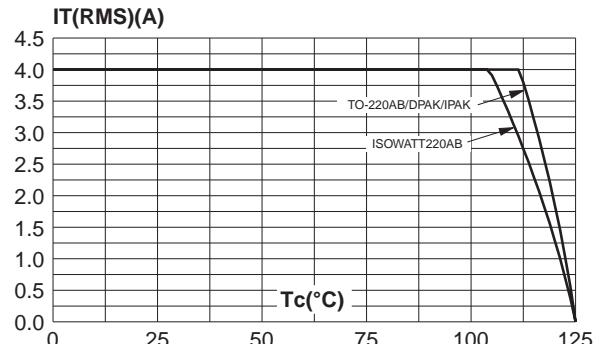


Fig. 3: Relative variation of thermal impedance versus pulse duration.

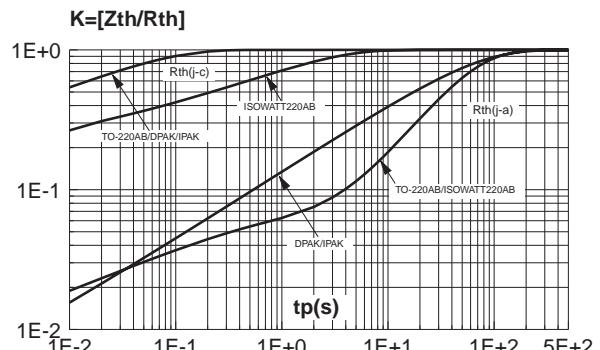


Fig. 5: Surge peak on-state current versus number of cycles.

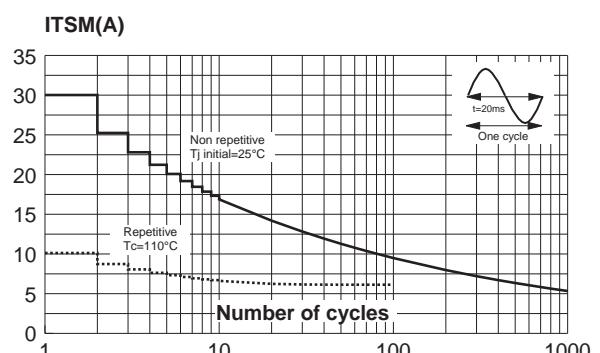


Fig. 6: Non-repetitive surge peak on-state current for a sinusoidal pulse with width $t_p < 10\text{ms}$, and corresponding value of I^2t .

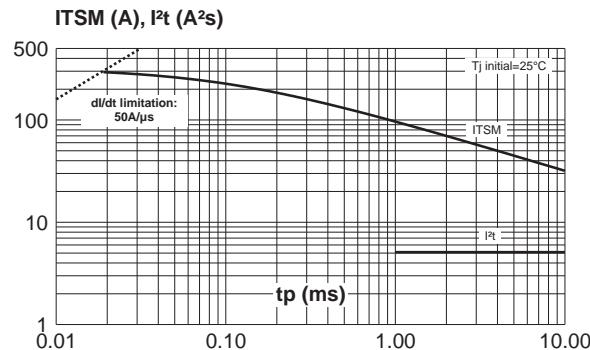


Fig. 8: Relative variation of critical rate of decrease of main current versus $(dV/dt)_c$ (typical values).

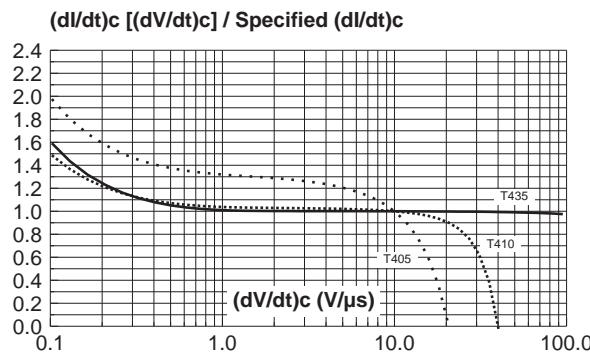


Fig. 10: DPAK thermal resistance junction to ambient versus copper surface under tab (printed circuit board FR4, copper thickness: $35\mu\text{m}$).

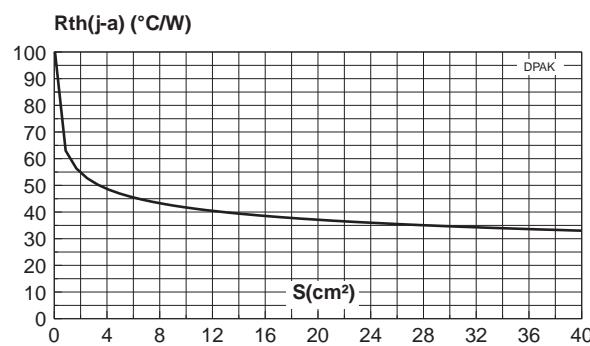


Fig. 7: On-state characteristics (maximum values).

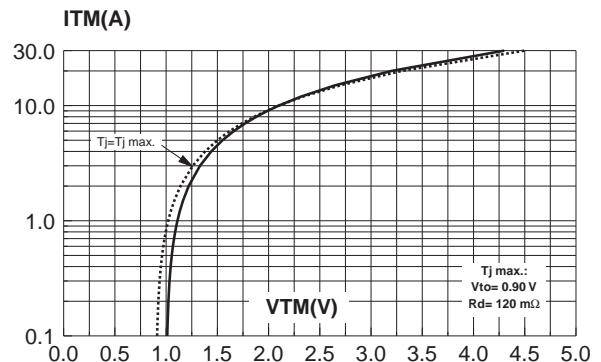
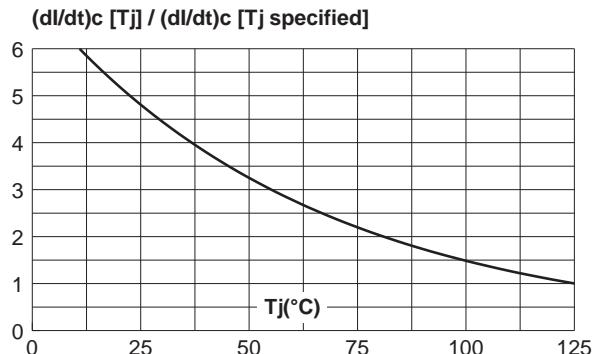


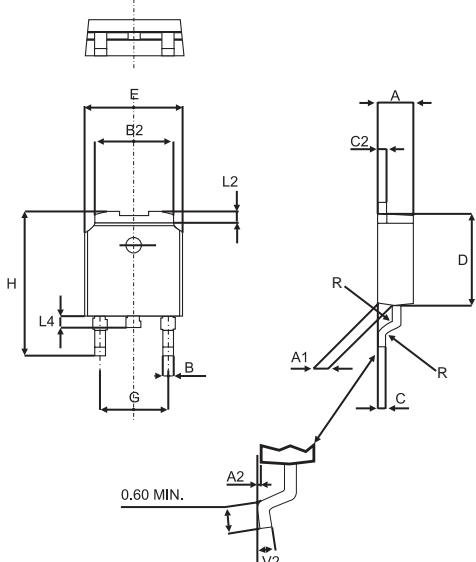
Fig. 9: Relative variation of critical rate of decrease of main current versus junction temperature.



T4 Series

PACKAGE MECHANICAL DATA

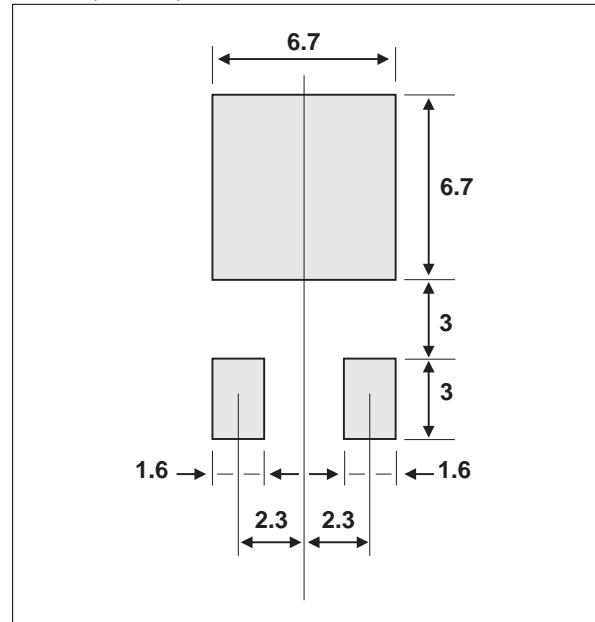
DPAK (Plastic)



REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max	Min.	Max.
A	2.20	2.40	0.086	0.094
A1	0.90	1.10	0.035	0.043
A2	0.03	0.23	0.001	0.009
B	0.64	0.90	0.025	0.035
B2	5.20	5.40	0.204	0.212
C	0.45	0.60	0.017	0.023
C2	0.48	0.60	0.018	0.023
D	6.00	6.20	0.236	0.244
E	6.40	6.60	0.251	0.259
G	4.40	4.60	0.173	0.181
H	9.35	10.10	0.368	0.397
L2	0.80 typ.		0.031 typ.	
L4	0.60	1.00	0.023	0.039
R	0.2 typ.		0.007 typ.	
V2	0°	8°	0°	8°

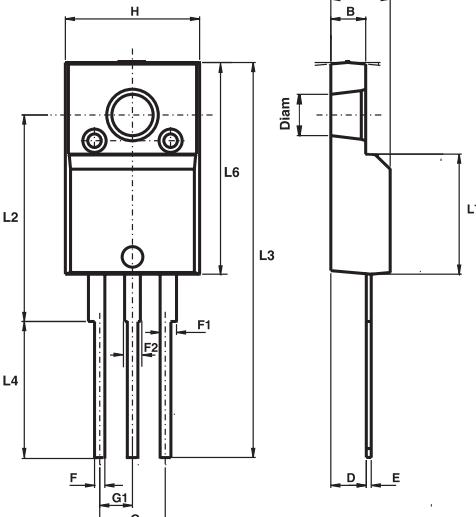
FOOTPRINT DIMENSIONS (in millimeters)

DPAK (Plastic)



PACKAGE MECHANICAL DATA

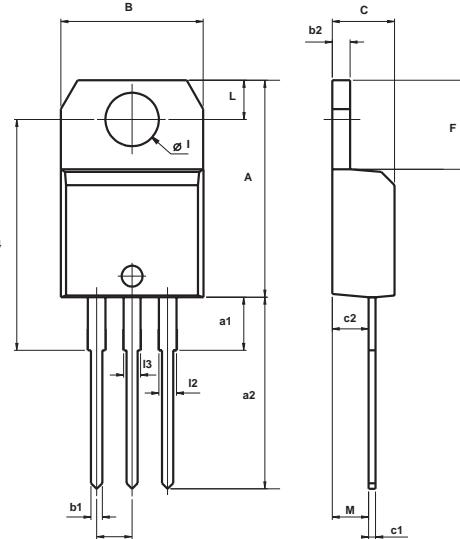
ISOWATT220AB (Plastic)



REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
B	2.50	2.70	0.098	0.106
D	2.50	2.75	0.098	0.108
E	0.40	0.70	0.016	0.028
F	0.75	1.00	0.030	0.039
F1	1.15	1.70	0.045	0.067
F2	1.15	1.70	0.045	0.067
G	4.95	5.20	0.195	0.205
G1	2.40	2.70	0.094	0.106
H	10.00	10.40	0.394	0.409
L2	16.00 typ.		0.630 typ.	
L3	28.60	30.60	1.125	1.205
L4	9.80	10.60	0.386	0.417
L6	15.90	16.40	0.626	0.646
L7	9.00	9.30	0.354	0.366
Diam	3.00	3.20	0.118	0.126

PACKAGE MECHANICAL DATA

TO-220AB (Plastic)

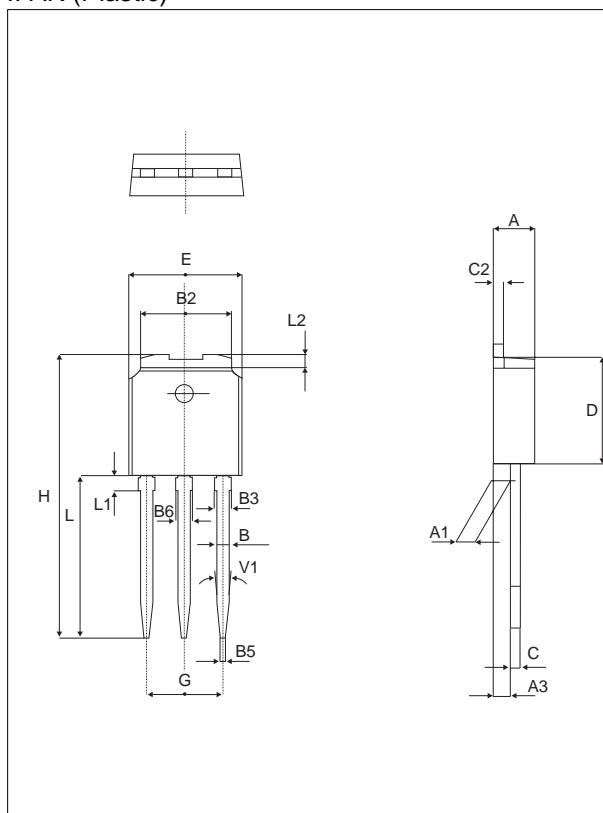


REF.	DIMENSIONS					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	15.20		15.90	0.598		0.625
a1		3.75			0.147	
a2	13.00		14.00	0.511		0.551
B	10.00		10.40	0.393		0.409
b1	0.61		0.88	0.024		0.034
b2	1.23		1.32	0.048		0.051
C	4.40		4.60	0.173		0.181
c1	0.49		0.70	0.019		0.027
c2	2.40		2.72	0.094		0.107
e	2.40		2.70	0.094		0.106
F	6.20		6.60	0.244		0.259
I	3.75		3.85	0.147		0.151
I4	15.80	16.40	16.80	0.622	0.646	0.661
L	2.65		2.95	0.104		0.116
I2	1.14		1.70	0.044		0.066
I3	1.14		1.70	0.044		0.066
M		2.60			0.102	

T4 Series

PACKAGE MECHANICAL DATA

IPIAK (Plastic)



REF.	DIMENSIONS					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.2		2.4	0.086		0.094
A1	0.9		1.1	0.035		0.043
A3	0.7		1.3	0.027		0.051
B	0.64		0.9	0.025		0.035
B2	5.2		5.4	0.204		0.212
B3			0.85			0.033
B5		0.3			0.035	
B6			0.95			0.037
C	0.45		0.6	0.017		0.023
C2	0.48		0.6	0.019		0.023
D	6		6.2	0.236		0.244
E	6.4		6.6	0.252		0.260
G	4.4		4.6	0.173		0.181
H	15.9		16.3	0.626		0.641
L	9		9.4	0.354		0.370
L1	0.8		1.2	0.031		0.047
L2		0.8	1		0.031	0.039
V1		10°			10°	

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